

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc2931hf#trpbf

(Engineering Calculation)

TSSOP

(printed on: 2020-07-11 18:11:42)

TOTAL MASS (g) : 0.071112

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.002169 | 1000000 | 30501.0371094 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.024098 | 962000 | 338872.28125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000000 | 0 | 0 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000000 | 0 | 0 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000000 | 0 | 0 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000751 | 30000 | 10560.7558594 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000163 | 1500 | 534.365783691 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000038 | 1500 | 534.365783691 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.025050 | 1000000 | 352259.53125 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.001770 | 1000000 | 24894.8222656 | | |
| | | External Plating Total: | | | | 0.001770 | 1000000 | 24894.8222656 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000683 | 1000000 | 9604.5234375 | | |
| | | Internal Plating Total: | | | | 0.000683 | 1000000 | 9604.5234375 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000743 | 750000 | 10448.2578125 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000248 | 250000 | 3487.43994141 | | |
| Die Attach Total: | | | | 0.000991 | 1000000 | 13935.6972656 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.005414 | 135000 | 76133.0625 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.034486 | 860000 | 484951.03125 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000201 | 5000 | 2826.51391602 | | |
| | | Encapsulation Total: | | | | 0.040101 | 1000000 | 563910.625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000348 | 1000000 | 4893.66552734 | | |
| | | | | | TOTAL MASS (g) : | 0.071112 | | |